

# Single N-channel MOSFET

## ELM4N28N15FDA-N

<https://www.elm-tech.com>

### ■General description

ELM4N28N15FDA-N uses advanced trench technology to provide excellent  $R_{ds(on)}$ , low gate charge and low gate threshold voltage.

### ■Features

- $V_{ds}=150V$
- $I_d=30A$  ( $V_{gs}=10V$ )
- $R_{ds(on)} = 46m\Omega$  ( $V_{gs}=10V$ )
- $R_{ds(on)} = 50m\Omega$  ( $V_{gs}=4.5V$ )

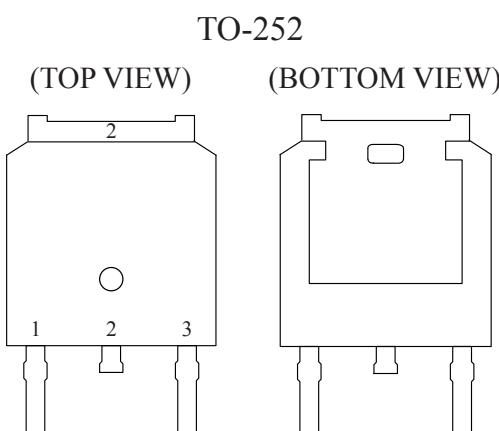
### ■Maximum absolute ratings

Parameter	Symbol	Limit	Unit	Note
Drain-source voltage	$V_{ds}$	150	V	
Gate-source voltage	$V_{gs}$	$\pm 20$	V	
Continuous drain current ( $V_{gs}=10V$ )	$I_d$	30	A	1
Tc=100°C		22		
Pulsed drain current	$I_{dm}$	60	A	2
Single pulsed avalanche energy	$E_{as}$	216	mJ	3
Avalanche current	$I_{as}$	38	A	
Total power dissipation	$P_d$	115	W	4
Storage temperature range	$T_{stg}$	-55 to 175	°C	
Operating junction temperature range	$T_j$	-55 to 175	°C	

### ■Thermal characteristics

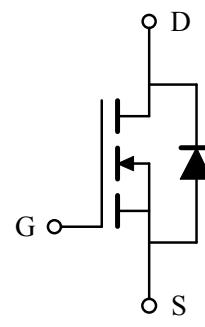
Parameter	Symbol	Typ.	Max.	Unit	Note
Thermal resistance junction-ambient	$R_{\theta ja}$	-	55.0	°C/W	1
Thermal resistance junction-case	$R_{\theta jc}$	-	1.3	°C/W	1

### ■Pin configuration



Pin No.	Pin name
1	GATE
2	DRAIN
3	SOURCE

### ■Circuit



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### ■Electrical characteristics

T<sub>j</sub>=25°C. Unless otherwise noted.

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit	Note
<b>STATIC PARAMETERS</b>							
Drain-source breakdown voltage	BVdss	V <sub>gs</sub> =0V, I <sub>d</sub> =250μA	150	-	-	V	
Static drain-source on-resistance	R <sub>ds(on)</sub>	V <sub>gs</sub> =10V, I <sub>d</sub> =20A	-	35	46	mΩ	2
		V <sub>gs</sub> =4.5V, I <sub>d</sub> =20A	-	37	50		
Gate threshold voltage	V <sub>gs(th)</sub>	V <sub>gs</sub> =V <sub>ds</sub> , I <sub>d</sub> =250μA	1.2	-	2.5	V	
Drain-source leakage current	I <sub>dss</sub>	V <sub>ds</sub> =120V, V <sub>gs</sub> =0V	-	-	1	μA	
		V <sub>ds</sub> =120V, V <sub>gs</sub> =0V, T <sub>j</sub> =55°C	-	-	5		
Gate-source leakage current	I <sub>gss</sub>	V <sub>gs</sub> =±20V, V <sub>ds</sub> =0V	-	-	±100	nA	
Forward transconductance	G <sub>f</sub> s	V <sub>ds</sub> =5V, I <sub>d</sub> =20A	-	55	-	S	
Continuous source current	I <sub>s</sub>	V <sub>gs</sub> =V <sub>ds</sub> =0V, Force current	-	-	30	A	1, 5
Diode forward voltage	V <sub>sd</sub>	V <sub>gs</sub> =0V, I <sub>s</sub> =1A	-	-	1.2	V	2
<b>DYNAMIC PARAMETERS</b>							
Input capacitance	C <sub>iss</sub>	V <sub>ds</sub> =25V, V <sub>gs</sub> =0V, f=1MHz	-	3755	-	pF	
Output capacitance	C <sub>oss</sub>		-	207	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>		-	160	-	pF	
<b>SWITCHING PARAMETERS</b>							
Total gate charge (4.5V)	Q <sub>g</sub>	V <sub>ds</sub> =75V, V <sub>gs</sub> =4.5V, I <sub>d</sub> =10A	-	40	-	nC	
Gate-source charge	Q <sub>gs</sub>		-	10	-	nC	
Gate-drain charge	Q <sub>gd</sub>		-	21	-	nC	
Turn-on delay time	t <sub>d(on)</sub>	V <sub>ds</sub> =50V, V <sub>gs</sub> =4.5V R <sub>gen</sub> =3.3Ω, I <sub>d</sub> =10A	-	18	-	ns	
Turn-on rise time	t <sub>r</sub>		-	20	-	ns	
Turn-off delay time	t <sub>d(off)</sub>		-	65	-	ns	
Turn-off fall time	t <sub>f</sub>		-	15	-	ns	
Reverse recovery time	t <sub>rr</sub>	I <sub>f</sub> =10A, di/dt=100A/μs	-	35	-	ns	
Reverse recovery charge	Q <sub>rr</sub>		-	120	-	nC	

#### NOTE :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width ≤ 300μs and duty cycle ≤ 2%.
3. The Eas data shows Max. rating . The test condition is V<sub>dd</sub>=25V, V<sub>gs</sub>=10V, L=0.3mH, I<sub>as</sub>=38A.
4. The power dissipation is limited by 150°C junction temperature.
5. The data is theoretically the same as I<sub>d</sub> and I<sub>dm</sub>, in real applications, should be limited by total power dissipation.

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## ■Typical characteristics

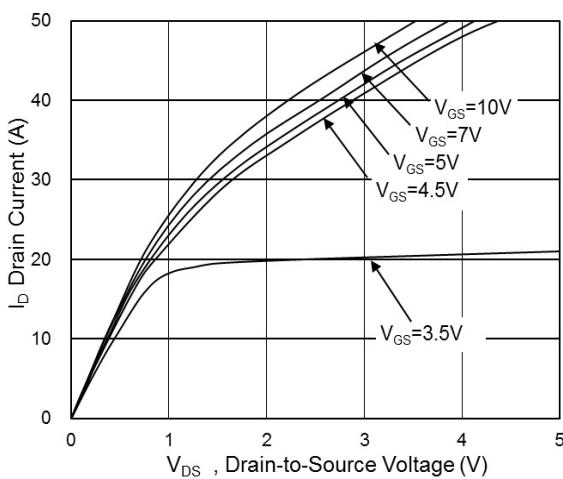


Fig.1 Typical Output Characteristics

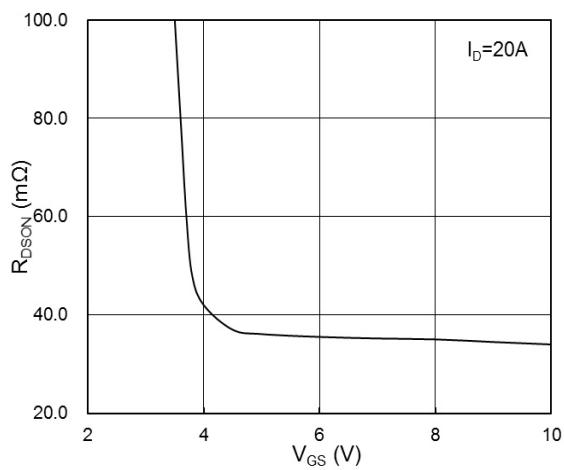


Fig.2 On-Resistance vs. Gate-Source

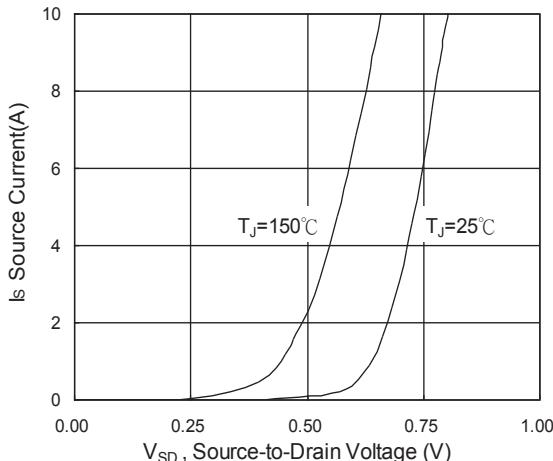


Fig.3 Forward Characteristics Of Reverse

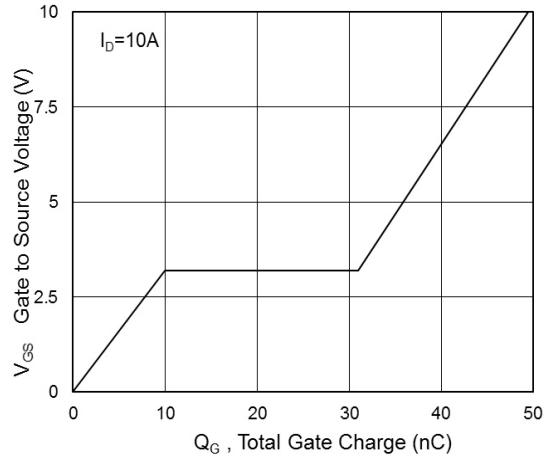


Fig.4 Gate-Charge Characteristics

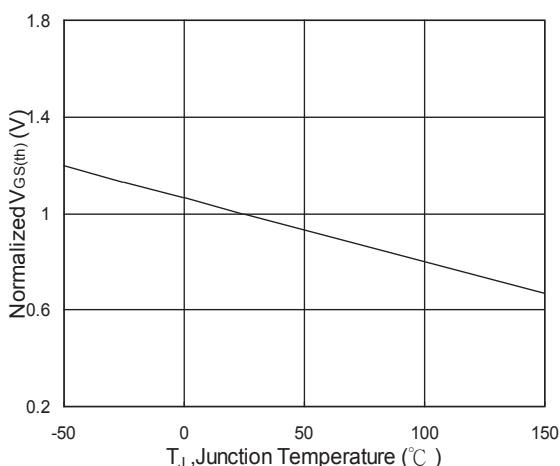


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

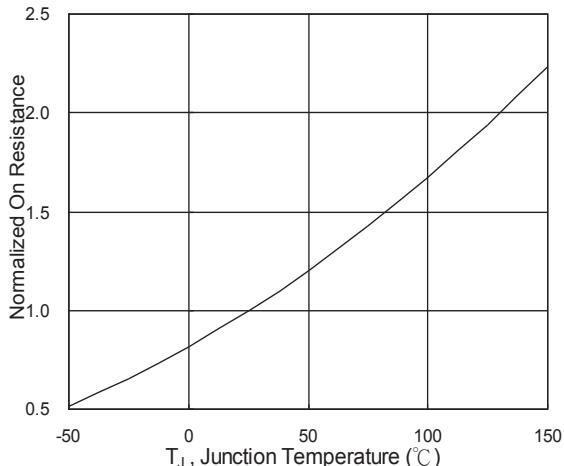


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

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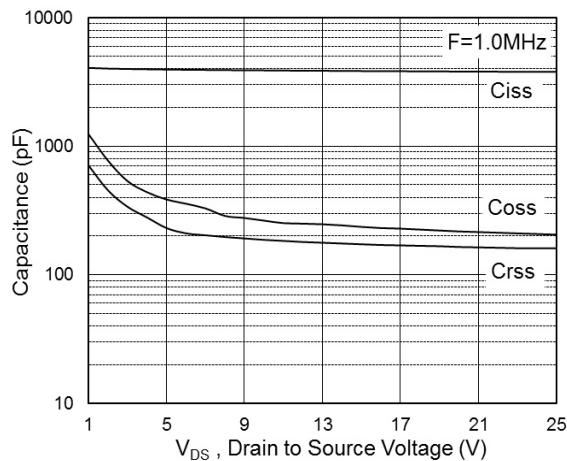


Fig.7 Capacitance

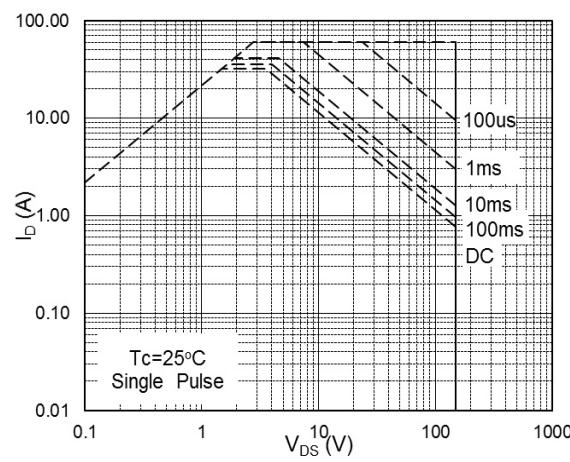


Fig.8 Safe Operating Area

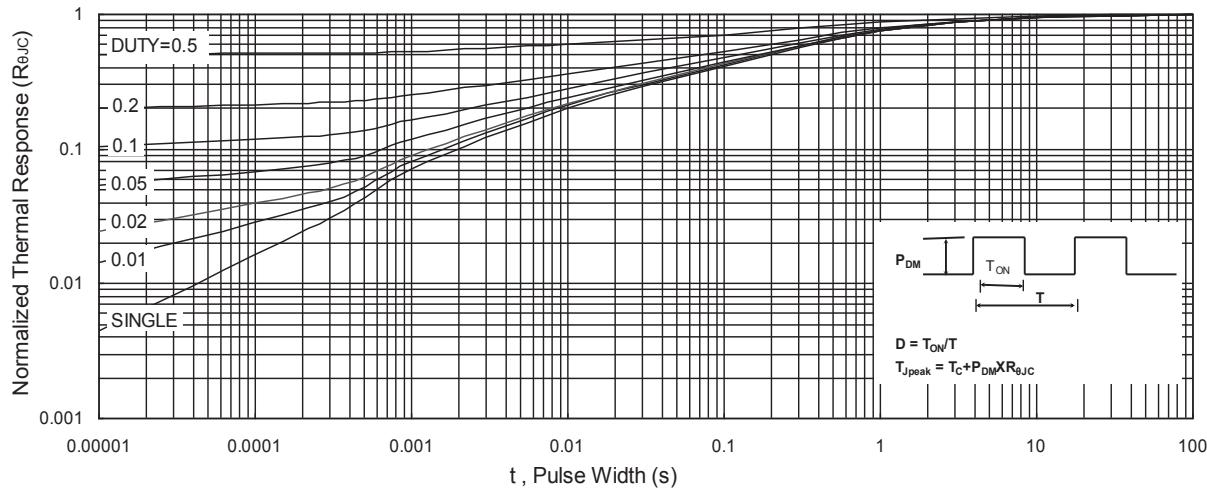


Fig.9 Normalized Maximum Transient Thermal Impedance

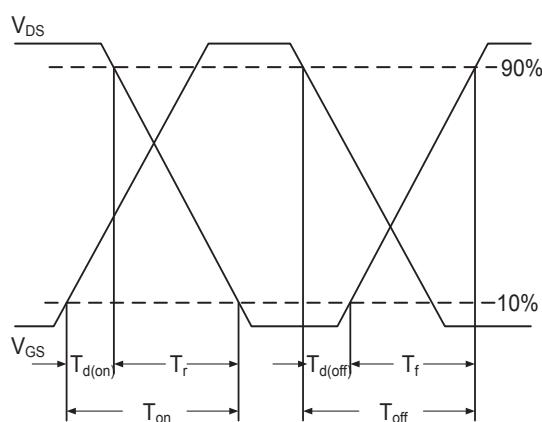


Fig.10 Switching Time Waveform

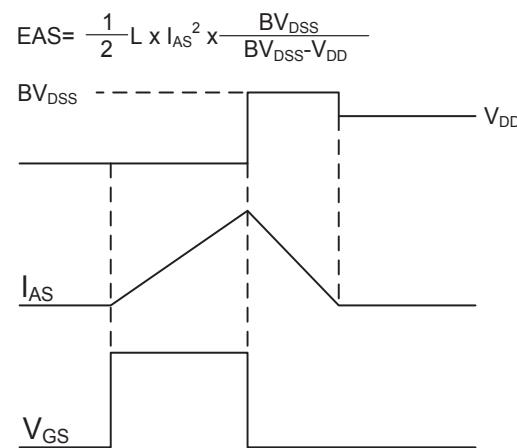


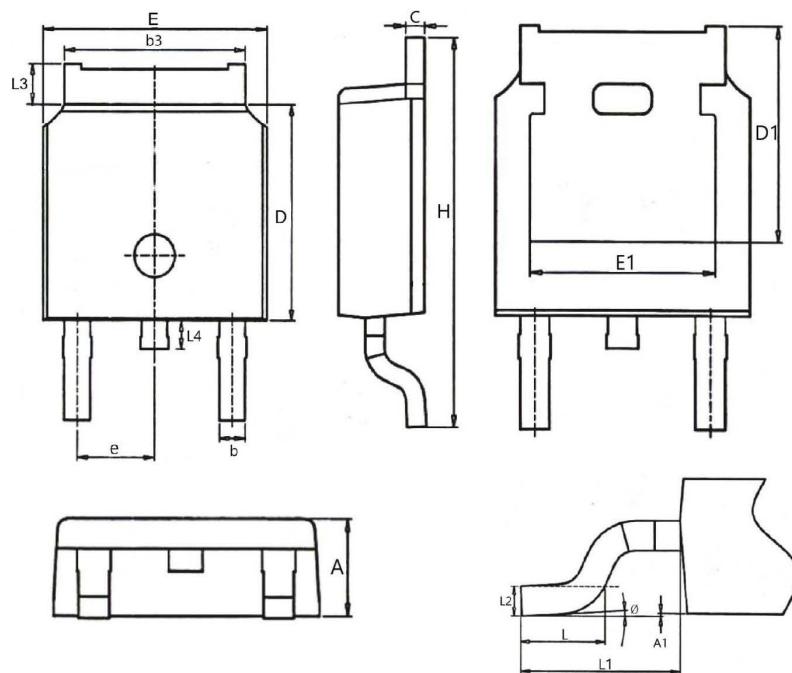
Fig.11 Unclamped Inductive Switching Waveform

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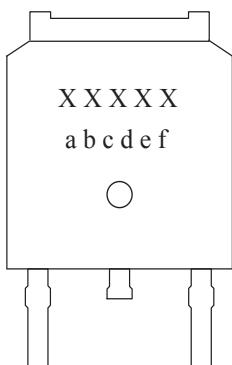
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## ■TO-252 dimension (2,500pcs/reel)



Symbols	Millimeters		Inches		Symbols	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	2.18	2.40	0.086	0.095	e	2.286BSC		0.09BSC	
A1	---	0.20	---	0.008	H	9.40	10.50	0.370	0.413
b	0.68	0.90	0.026	0.036	L	1.38	1.78	0.054	0.070
b3	4.95	5.46	0.194	0.215	L1	2.90REF		0.114REF	
c	0.43	0.89	0.017	0.035	L2	0.51BSC		0.020BSC	
D	5.97	6.22	0.235	0.245	L3	0.88	1.28	0.034	0.050
D1	5.300REF		0.209REF		L4	0.50	1.00	0.019	0.039
E	6.35	6.73	0.250	0.265	θ	0°	8°	0°	8°
E1	4.32	---	0.170	---					

## ■Marking



Symbols	Content
xxxxx	Product code
a	Yearly code: 2019=K, 2020=L, 2021=M...
b, c	Weekly code: 01 to 53
d, e	Sequence: 01 to 99 or 0A to 0Z
f	Assembly code: A to Z (I, O excepted)